



NOTES:

1. MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0
- 1.2 CONTACT: COPPER ALLOY
- 1.3 FITTING NAIL: COPPER ALLOY

2. FINISH:

- 2.1 CONTACT: 50 $\mu$  MIN. NICKEL UNDERPLATING OVERALL.  
1:GOLD FLASH ON CONTACT AND SOLDER AREA  
C:15 $\mu$  GOLD ON CONTACT AND SOLDER AREA  
N:100 $\mu$  MATTE TIN PLATING.
- 2.2 FITTING NAIL: 50 $\mu$  MIN. NICKEL UNDERPLATING OVERALL.  
N:80 $\mu$  MIN. MATTE TIN PLATING
- 3. REFLOW SOLDER CAPABLE TO 260°C  
PER ACES SPEC.
- 4. SPEC. PLS. REFER TO PS-51415-XXXX-XXX
- 5. PACKAGE PLS. REFER TO 51415-XXXX-XX-TRP.
- 6. PART NUMBER

51415-XXX X X-XXX

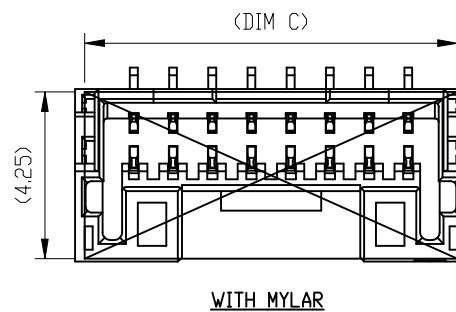
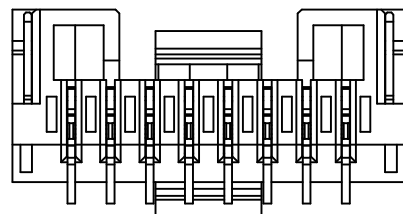
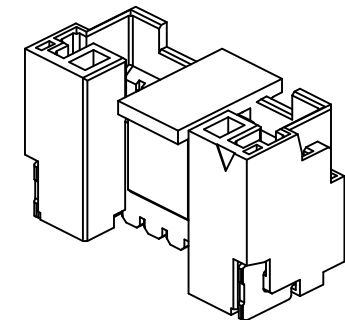
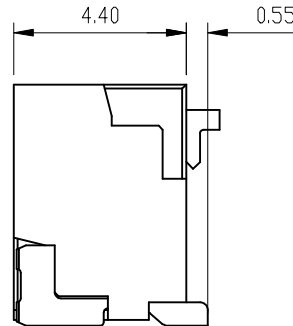
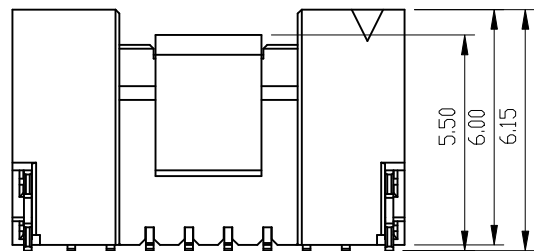
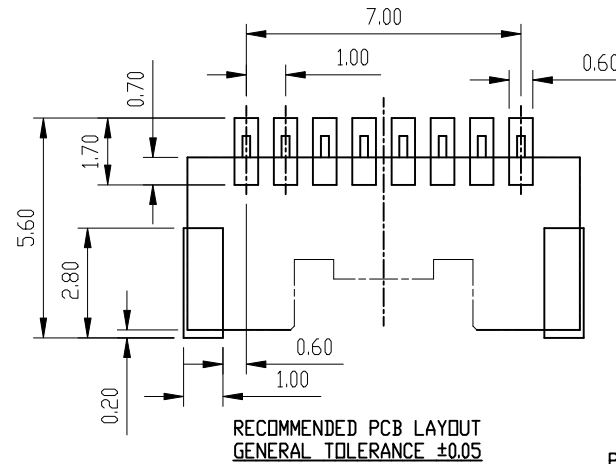
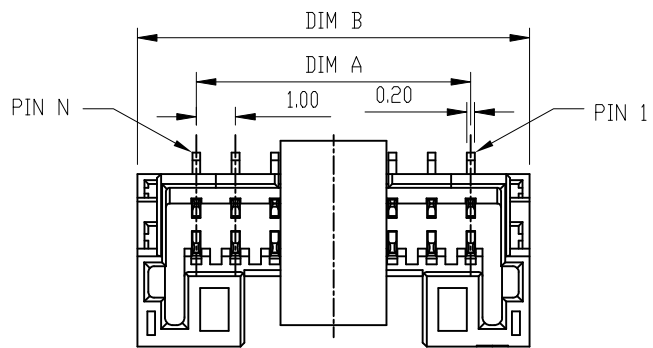
XXX	LOGO	COLOR
001	ACES	NATURAL

PACKING

- 0:TAPE&REEL
- 4:TAPE&REEL WITH MYLAR
- 7:TAPE&REEL WITH COVER

PLATING

- 1:GOLD FLASH PLATING
- C:15 $\mu$  GOLD ON CONTACT AREA
- N:100 $\mu$  MATTE TIN

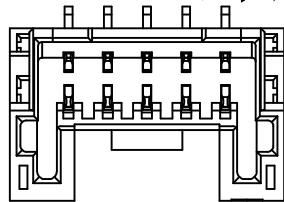


CKTS	A	B	C
5	4.00	7.00	6.50
8	7.00	10.00	9.50
10	9.00	12.00	11.50
15	14.00	17.00	16.50

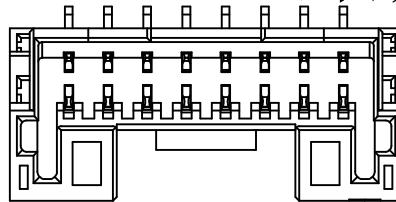
<b>QUALITY SYMBOLS</b> MAJOR CRITICAL <b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b> X. $\pm 0.5$ .X $\pm 0.25$ .XX $\pm 0.15$ .XXX $\pm 0.1$ ANGLES $\pm 2^\circ$	DRAWN BY Sun,Ya Jie CHECKED BY Xu,Zhi Yong APPROVED BY Xu,Zhi Yong	DATE 23'/02/08 DATE 23'/02/08 DATE 23'/02/08	 <b>ACES ELECTRONICS</b> 1.0 mm WTB Wafer Conn. SMT S/R S/T TYPE.
	UNITS mm SCALE 1 : 1	 SHEET NO. 1 OF 2	







5 PIN外觀



8~15PIN外觀



QUALITY SYMBOLS MAJOR  CRITICAL 	DRAWN BY Sun,Ya Jie	DATE 23'/02/08		
	CHECKED BY Xu,Zhi Yong	DATE 23'/02/08		
GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	APPROVED BY Xu,Zhi Yong	DATE 23'/02/08	TITLE 1.0 mm WTB Wafer Conn. SMT S/R S/T TYPE.	
	UNITS mm		SIZE A4	RFQ NO. 1811062
	SCALE 1 : 1	SHEET NO. 2 OF 2	REV C	DWG NO. 51415-XXXXX-XXX